

## [SNAPLIGHT]

**MULTIFUNCTION LASER WITH A UNIQUE EXTENDED FOV, SUITABLE FOR  $\mu$ MACHINING, SURFACE PREPARATION, AND DIGITAL SINTERING.**



## MICROMETRIC PRECISION

The **SNAP LIGHT** module expands the MSTECH software suite with a **high-precision laser** system designed for critical application in electronic & semicon manufacturing. It performs ultra- accurate **ablation, marking, sintering, cleaning, and edge-finishing operations** with full digital control.

**SNAP LIGHT** executes with micrometric precision, ensuring maximum efficiency, repeatability, and reduced process errors.

### LASER TECHNOLOGY

- » Laser spot:  $\geq 40 \mu\text{m}$ .
- » Marking area indicator.
- » Internal barcode generator.
- » Marca full graphics PC Software.
- » Available as an OEM Kit or within MSTECH Europe platform compatible with **SNAP MOTION**, and **SMARTBOX** (optional).



MICROMETRIC PRECISION

// CORE FUNCTIONS

- Ablation: Remove unwanted materials or reduce excess for uniformity.
■ Cleaning: Strip solder masks, clean oxidated contacts, remove flux.
■ Marking: Precise laser marking.
■ Sintering: Material sintering.
■ Edging: Define contours.
■ μmachining: Open vias.

// APPLICATIONS

- » Surface activation & cleaning (oxides, residues and contaminants).
» Sintering & curing of functional inks, coatings, and polymers.
» Laser marking & localized ablation.
» Via etching & micro-machinins.
» Material removal & thickness trimming.
» Precision cutting, slotting & depaneling.



WORKFLOW EFFICIENCY

[SNAP VISION] identifies → [SNAP LIGHT] executes →

Result: maximum precision, repeatability, and reduced errors.



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